

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ISC010N06NM5	**Issued**	08. April 2022
MA#	MA005710662		
Package	PG-TSON-8-3	**Weight***	124.02 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.102	2.50	2.50	25012	25012
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		73	
	non noble metal	zinc	7440-66-6	0.036	0.03		292	
	non noble metal	iron	7439-89-6	0.725	0.58		5846	
	non noble metal	copper	7440-50-8	29.440	23.74	24.36	237379	243590
wire	noble metal	gold	7440-57-5	0.053	0.04	0.04	429	429
encapsulation	organic material	carbon black	1333-86-4	0.092	0.07		745	
	plastics	epoxy resin	-	4.759	3.84		38375	
	inorganic material	silicondioxide	60676-86-0	41.356	33.35	37.26	333456	372576
leadfinish	non noble metal	tin	7440-31-5	1.343	1.08	1.08	10827	10827
plating	noble metal	silver	7440-22-4	0.030	0.02	0.02	244	244
solder	non noble metal	tin	7440-31-5	0.066	0.05		528	
	noble metal	silver	7440-22-4	0.082	0.07		661	
	non noble metal	lead	7439-92-1	3.130	2.52	2.64	25235	26424
heat sink clip	inorganic material	phosphorus	7723-14-0	0.009	0.01		76	
	non noble metal	iron	7439-89-6	0.032	0.03		255	
	non noble metal	copper	7440-50-8	31.570	25.46	25.50	254555	254886
heatspreader	inorganic material	phosphorus	7723-14-0	0.002			20	
	non noble metal	zinc	7440-66-6	0.010	0.01		79	
	non noble metal	iron	7439-89-6	0.196	0.16		1584	
	non noble metal	copper	7440-50-8	7.978	6.43	6.60	64329	66012
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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